Special Issue

Tin-Based Joint Reliability

Message from the Guest Editor

Enhancing the reliability of tin-based solder joints has been being a forward position and a hot topic in the field of microelectronic packaging. Significant advances in this subject have been achieved as a result of interdisciplinary research on the related fields of doping technique, surface engineering, materials characterization, electrochemical processing and numerical simulation. Based on theoretical analyses and scientific researches, industries have shown a growing interest in utilizing relevant techniques as valuable tools for improvement of the microelectronics and the surface mount technology. This special issue on “Tin-Based Joint Reliability” intends to collect the last developments in the field, written by well-known researchers who have contributed significantly in tin-based alloy manufacturing, surface modification of the base metal, materials characterization of tin-based solder joints, or the numerical simulation of related intermetallic compounds.

Guest Editor

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Message from the Editor-in-Chief

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

Editor-in-Chief

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